广东盈骅新材料科技有限公司
GUANGDONG HINNO-TECH CO.,LTD.

Y-206BSM

Blcak ,Low CTE,High modulus Laminate for IC Packages

产品特点:

- 低膨胀、低收缩，有效降低 IC 封装基板翘曲
- 高模量(高弹性率)
- 优异的耐热性
- 无卤、高 Tg220℃
- 黑色和良好的光遮蔽性能
- 优异的厚度均匀性

应用领域:

CSP、BGA、FC-PKG 等封装用基板。

Key Features:

- Low CTE and low shrinkage, effective to reduced the warpage of substrate for IC PKG
- High modulus,
- Excellent heat resistance
- Halogen-free and Tg220℃
- Black and good light blocking
- Excellent uniformity of thickness

Applications:

Substrates for CSP、BGA、FC-PKG etc.

General properties:

Item	Condition	Units	Typical value
红光透过性 Red Light Permeability	Hinno test method	%	0
玻璃化转变温度 Glass Transition Temperature	DMA	℃	220
X,Y 轴方向膨胀系数 X,Y-CTE	TMA	ppm/℃	6～8
弯曲模量 Flexural Modulus	A	GPa	28
杨氏模量 Young’s Modulus	A	GPa	30
288℃分层时间 T288	TMA	min	＞60
浸锡测试 Solderability	288℃	s	＞300
剥离强度 Peel Strength（Hoz Copper Foil）	288℃/10s	lb/inch	5.1
弯曲强度 Flexural Strength	E-2/150	MPa	560
热失重(weight loss 5%) Decomposition temperature	TGA	℃	380

热导率 Thermal conductivity	ASTM-D5470	W/(m*k)	0.88
吸水率 Moisture Absorption	D-24/23	%	0.08

Specimen thickness：0.4mm or 0.8mm. Test Method is according to IPC TM-650 or National Standard Test Method.